

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6885950"	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/15 20:12
L2	1	"7065239"	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/15 20:21
L3	2312	438/14.ccls.	US-PGPUB; USPAT; USOCR	AND	OFF	2006/12/15 20:22
L4	1801	438/14.ccls. wafer	US-PGPUB; USPAT; USOCR	AND	OFF	2006/12/15 20:22
L5	541	438/14.ccls. wafer die	US-PGPUB; USPAT; USOCR	AND	OFF	2006/12/15 20:22
L6	253	438/14.ccls. wafer die parameters	US-PGPUB; USPAT; USOCR	AND	OFF	2006/12/15 20:22
L7	21	703/13.ccls. wafer die parameters	US-PGPUB; USPAT; USOCR	AND	OFF	2006/12/15 20:22
L8	23	703/14.ccls. wafer die parameters	US-PGPUB; USPAT; USOCR	AND	OFF	2006/12/15 20:22
L9	10	702/150.ccls. wafer die parameters	US-PGPUB; USPAT; USOCR	AND	OFF	2006/12/15 20:22
S1	3	2005/0132308	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/14 15:50
S2	2	"20050132308"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/11 10:40
S3	8	"20050132308" "20030229410" "20040162692" "20050060336"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/11 10:54

EAST Search History

S4	24	"20060059452" "20050227587" "20060031788" "6070004".pn. "20060085155" "20040267477" "20050278878" "7039556".pn. "7013192".pn. "6986112".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/11 11:05
S5	21	("6776630" "6477685" "6393602" "6185707" "6067507" "6982920" "6787190").pn. "200201219"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/12 09:38
S6	9	(virtual adj2 die) wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/12/12 09:38
S7	2	"20060064268"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/14 19:20
S8	2	"6521467".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/14 19:20
S9	5	("4853624" "4908570" "5003253" "5654204" "6194739").PN. OR ("6521467"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/14 19:24
S10	1	"6294397".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/14 19:24
S11	15	("3751647" "3842491" "3983479" "4855253" "5159752" "5514974" "5576223" "5773315" "5801394" "5959459").PN. OR ("6294397"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/15 14:58
S12	1	"7146297"	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/15 19:19

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wafer max-min normalize

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Patent Search

Patents 1 - 10 of 13 on **wafer max-min normalize** (0.00 seconds)

Method to mathematically characterize a multizone carrier

US Pat. 6468131 - Filed Nov 28, 2000 - SpeedFam-IPEC Corporation

A second **wafer** may then be polished using this new pattern and a second removal

... removal profile may be found as: where $RR(i)-m'n \max - \min RR_{\infty}(i)$ is the ...

Pad break-in method for chemical mechanical polishing tool which polishes with ceria-based slurry

US Pat. 7070484 - Filed May 21, 2004 - Mosel Vitelic, Inc.

Thus **wafer** numbers 19-23 are not counted in calculation of the batch average.

... Thick (A) n/a n/a n/a 4979 n/a n/a n/a 4968 Oxide Thick Range (**max-min**, ...

Projection electron beam lithography apparatus and method employing an estimator

US Pat. 7050957 - Filed Aug 29, 2001 - Agere Systems Inc.

... fixed in the whole time-frame of one **wafer** exposure, then changed but fixed

again for a second **wafer** 4Q contrast(*i*)=[**Max-Min**]/[Max+Min]@step k exposure. ...

Exposure method and apparatus

US Pat. 6813000 - Filed Jul 28, 2000 - Nikon Corporation

It is assumed that the **wafer** stands still, and the exposure area 46 is relatively

... the correction (**max-min** correction) is performed for the AF control to ...

Method and apparatus for scheduling workpieces with compatible processing requirements

US Pat. 6782302 - Filed Aug 30, 2002 - Advanced Micro Devices, Inc.

... **Max-Min**) C=Min In some cases, a partial function may be passed in a response.

In such a partial function the arguments of some 45 of the pefs are fixed. ...

Method and apparatus for generating a multi-dimensional cost function

US Pat. 6904329 - Filed Aug 30, 2002 - Advanced Micro Devices, Inc.

... **Max-Min**) Such a composite function may be communicated by 40 sending the ...

)/(**Max-Min**) C=Min 45 In some cases, a partial function may be passed in a ...

PROCESS TOOL

US Pat. 7127310 - Filed Aug 30, 2002 - budget The X

...)/(**Max-Min**) 13° to Vmchase Passing bffore the expiration period. ...

Budget components may also be provided to advance lots In some cases, ...

Method and apparatus for evaluating bids for scheduling a resource

US Pat. 6801819 - Filed Aug 30, 2002 - Advanced Micro Devices, Inc.

)(sum(pefs)-Min)/(**Max-Min**) 25 Such a composite function may be communicated by

...)/(**Max-Min**) 40 C=Min 45 In some cases, a partial function may be passed ...

Automated repetitive array microstructure defect inspection

US Pat. 7065239 - Filed Oct 24, 2001 - Applied Materials, Inc.

... current across a **wafer** result in background and contrast differences. ...

and minimum (eg Range=(max-min)/ (max+min)) over the cell-sized portion. ...

Method and apparatus for process endpoint prediction based on actual thickness measurements

US Pat. 5503707 - Filed Sep 22, 1993 - Texas Instruments Incorporated

If the raw process rate is outside of this **max/min** window, the thickness sample ... to see if the previous **wafer** layers have been properly pro- 5Q cessed, ...

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wafer poisson

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Patent Search

Patents 1 - 10 of 155 on **wafer poisson** (0.00 seconds)

Method, apparatus, and computer program of searching for clustering faults in semiconductor device manufacturing

US Pat. 6885950 - Filed Aug 20, 2001 - Kabushiki Kaisha Toshiba

(1) The **Poisson** distribution, therefore, is effective to represent random electrical faults. 40 When there are clustering electrical faults in a **wafer** 45 ...

Apparatus and method for calibration of patterned **wafer** scanners

US Pat. 5383018 - Filed Dec 28, 1992 - National Semiconductor Corporation

1, **wafer** can be modeied by a **poisson** distribution, then for there is shown a cross-sectional view of an unpatterned n>50) the **poisson** distribution tends ...

Film stress measurement system having first and second stage means

US Pat. 5118955 - Filed May 26, 1989 - Ann Koo

... or more film layers are formed on the surface of a single semiconduc-to **wafer**.
... substrate portion of the **wafer**, the **Poisson** ratio for the substrate, ...

System and method for introducing multiple component-type factors into an integrated circuit yield prediction

US Pat. 6611729 - Filed Mar 7, 2000 - Agere Systems Inc.

2 on the semiconductor **wafer** 110. The second routine 320, associated with the first ... may be represented, using the **Poisson** function, respectively as: ...

System for measuring the curvature of a semiconductor **wafer**

US Pat. 5227641 - Filed Nov 18, 1991 - Frontier Semiconductor Measurements, Inc.

If In the art of fabricating semiconductor wafers, it is of the **wafer** ... of the **wafer**, the **Poisson** ratio for beam of light reflected by the surface; ...

Methods and systems for predicting IC chip yield

US Pat. 6751519 - Filed Oct 24, 2002 - KLA-Tencor Technologies Corporation

The **Poisson** yield model is derived from the binomial distribution. ... If this is noi the lasi process, a 65 produci **wafer** lesi yield may then ...

Apparatus and method for plasma-processing

US Pat. 5695566 - Filed May 22, 1996 - Matsushita Electric Industrial Co.,Ltd.

The convex surface the silicon **wafer** is bent or deflected on condition that the ... and 0.42 of **Poisson** ratio is applied, and for the silicon **wafer** of 12 ...

Method and apparatus for radiation detection

US Pat. 5821541 - Filed Jan 15, 1997

The inherent energy resolution, R7, is 0.6% if the recoil electron stops in one silicon **wafer** by assuming a **Poisson** process. ...

Electric device inspection method and electric device inspection system

US Pat. 6539272 - Filed Feb 1, 2000 - Hitachi, Ltd.

However, this method must be performed on the premise that defects occur randomly on the **wafer** and that the inspection results follow the **Poisson** ...

Piezoelectric resonator and method for fabricating the same

US Pat. 6243933 - Filed May 3, 1999 - Matsushita Electric Industrial Co., Ltd.

In a prior art resonator made of one **wafer**, a half 10 wavelength is excited in ... curve thereof having a **Poisson** ratio equal to or 30 smaller than a third. ...

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wafer "virtual die"

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Patent Search

Patents 1 - 1 of 2 on wafer "virtual die". (0.00 seconds)

Surface inspection system

US Pat. 5864394 - Filed Sep 29, 1995 - Kla-Tencor Corporation

In the case of a non-patterned **wafer**, it is sometimes useful to define a **virtual die** and a corresponding **virtual die** grid, so that the definition of the ...

wafer "virtual die"

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